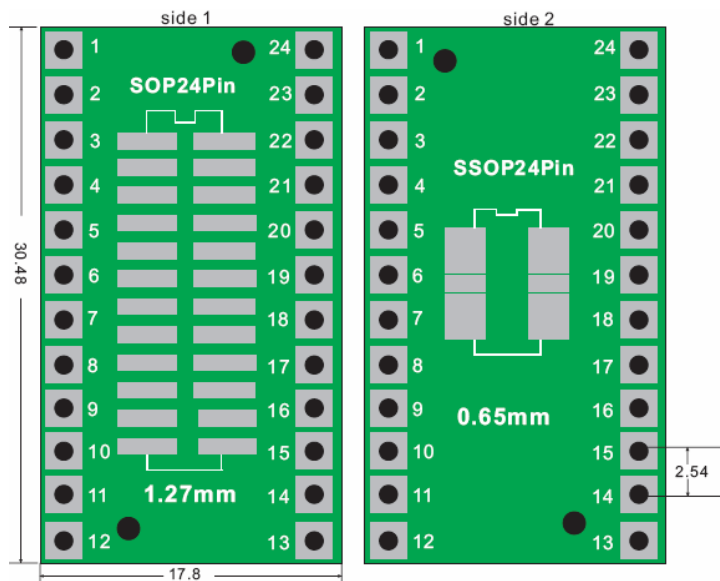


SMD package to DIP Converter Board

Item no. 1274816

Version 02/15



Function:
SOP24 & SSOP24 package to DIP

Technical Data:

Board Material	FR-4
SMD package	SOP24 (side 1) SSOP24 (side 2)
Pitch	1.27 (Side 1) 0.65 (Side 2)
Board Thickness	1.6mm ± 0.1mm
Surface Technioque	Spray tin 5-8um
Copper Thickness	35um ± 5um
Solderability	260°C at 3s - 1.1%
Flammability	V-0
Surface Resistivity	1.0 x 10 ⁶ MΩ
Volume Resistivity	1.0 x 10 ⁸ MΩ - cm
Arc Resistance	125sec.

Distributed by Conrad Electronic SE

This data sheet is a publication by Conrad Electronic SE, Klaus-Conrad-Str. 1, D-92240 Hirschau (www.conrad.com). All rights including translation reserved. Reproduction by any method, e.g. photocopy, microfilming, or the capture in electronic data processing systems require the prior written approval by the editor. Reprinting, also in part, is prohibited. This data represent the technical status at the time of printing. Changes in technology and equipment reserved.

© Copyright 2013 by Conrad Electronic SE.